

Notice of References CitedApplication/Control No.
10/785,345Applicant(s)/Patent Under
Reexamination
GLIDDEN ET AL.Examiner
Thomas J. MageeArt Unit
2811

Page 1 of 1

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*A copy of this reference is not being furnished with this Office action. (See MPEP § 707.05(a).)
Dates in MM-YYYY format are publication dates. Classifications may be US or foreign.